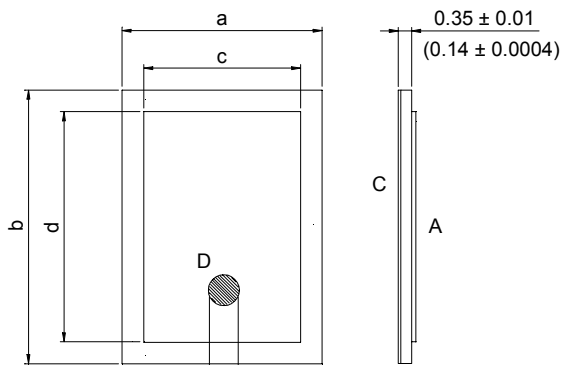


SCHOTTKY DIE 150 x 180 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

2. CONTROLLING DIMENSION: (INCH).

3. DIMENSIONS AND TOLERANCES:

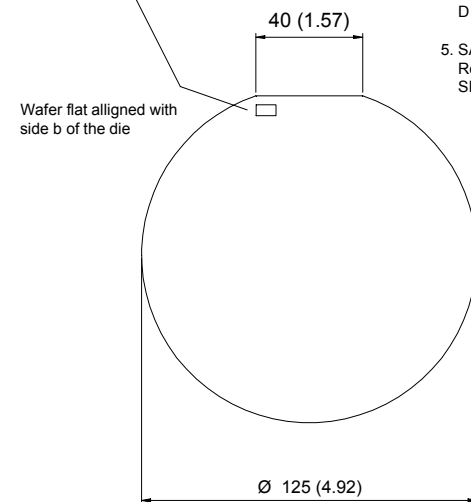
- a = 4.57 + 0, - 0.05
(0.180 + 0, - 0.002)
- b = 3.81 + 0, - 0.05
(0.150 + 0, - 0.002)
- c = 4.42 + 0, - 0.003
(0.174 + 0, - 0.0001)
- d = 3.66 + 0, - 0.003
(0.144 + 0, - 0.0001)
- Ø = 0.7 ± 0.1
(0.03 ± 0.004)

4. LETTER DESIGNATION:

- A = Anode (Top Metal)
- C = Cathode (Back Metal)
- D = Reject Ink Dot (only on non-conforming dies)

5. SAWING:

- Recommended Blade
- SEMITEC S1025 QS00 Blade



NOT TO SCALE

**NOTE: 10 mils die thickness is available on specific request only.
 Contact factory for information.**

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Typ. I _R @ 25°C (μA)	Typ. I _R @ 125°C (mA)	Max. V _F @ I _F (V)	Package Style
SC180R015x5x	125	15	n.a. contact factory			
SC180S020x5x	150	20	n.a. contact factory			
SC180S030x5x	150	30	n.a. contact factory			
SC180S045x5x	150	45	300	145	0.49 @ 20A	TO-247
SC180S060x5x	150	60	250	130	0.53 @ 20A	TO-247
SC180H045x5x	175	45	40	35	0.64 @ 30A	DO-4
SC180H100x5x	175	100	20	13	0.77 @ 20A	TO-247
SC180H150x5x	175	150	n.a. contact factory			

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC180xxxxA5x	Wire Bondable	–	Al 30 kÅ	–	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC180xxxxS5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

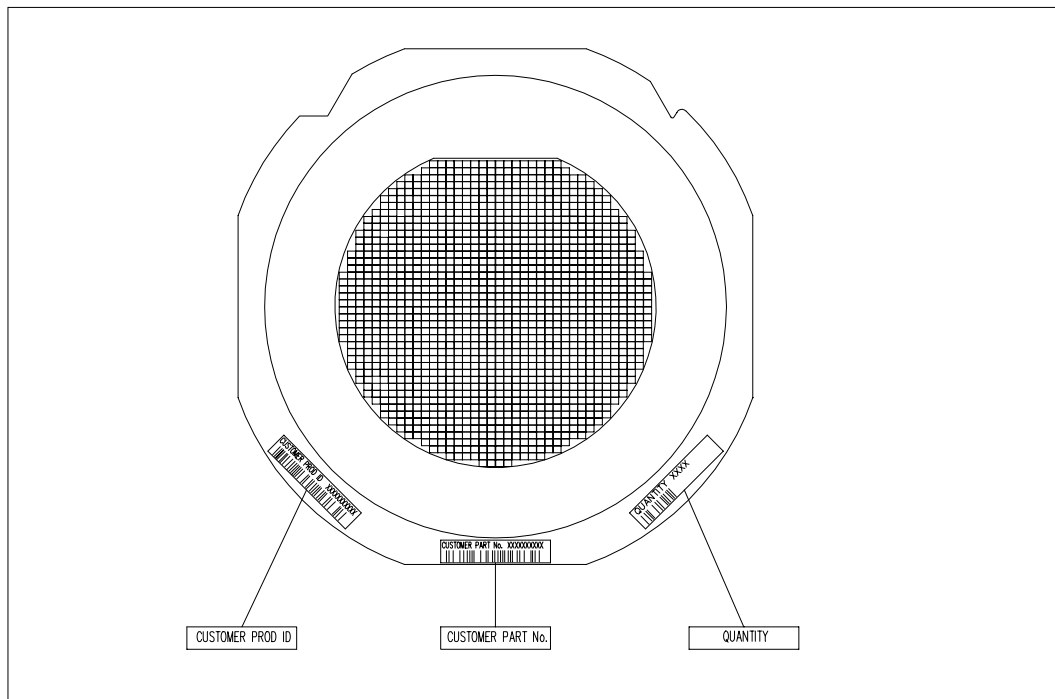
Device #	Description	Minimum Order Quantity Die in Sale Package
SC180xxxx5B	Inked Probed Unsawn Wafer (Wafer in Box)	560
SC180xxxx5R	Probed Die in Tape & Reel	n.a.
SC180xxxx5P	Probed Die in Waffle Pack	560
SC180xxxx5F	Inked Probed Sawn Wafer on Film	560

Ordering Information Table

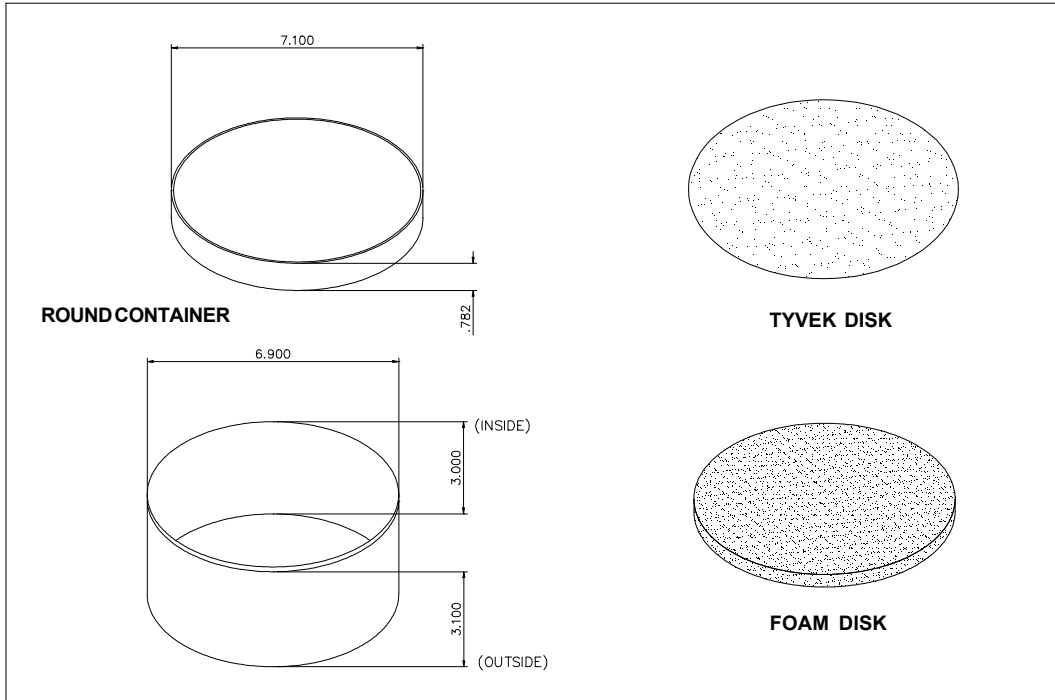
Device Code						
SC	180	H	100	S	5	B
1	2	3	4	5	6	7

<ul style="list-style-type: none"> 1 - Schottky Die 2 - Chip Dimension in Mils 3 - Process (see Electrical Characteristics Table) 4 - Voltage code: Code = V_{RRM} 5 - Chip surface metallization (see Mechanical Data Table) 6 - Wafer Diameter in inches 7 - Packaging (see Packaging Table) 	H = 830 Process R = OR'ing Process S = Standard Process
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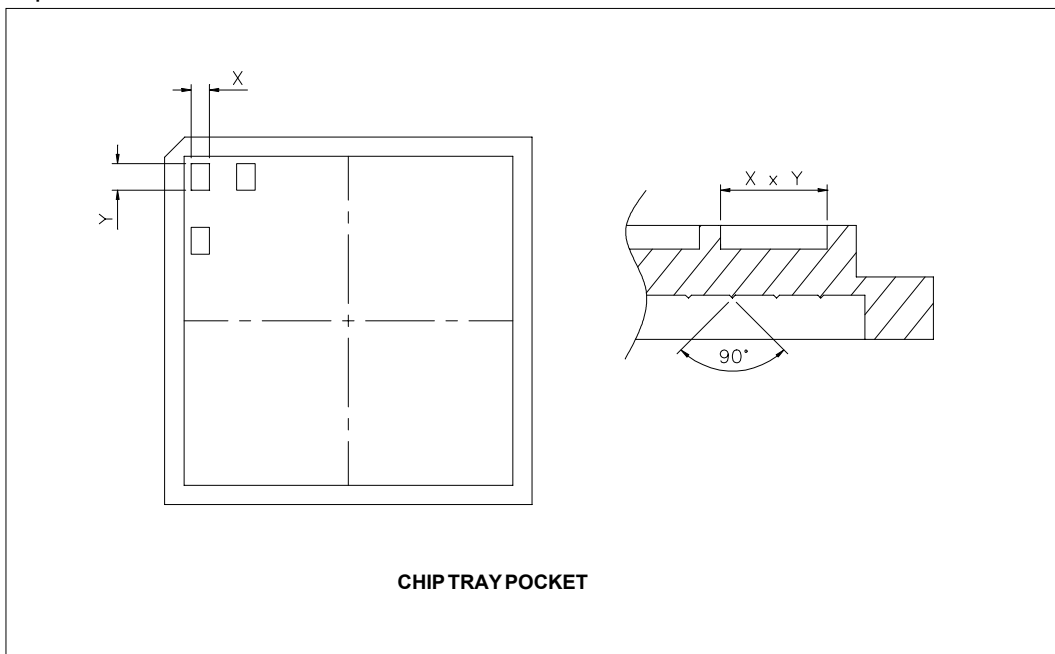
Wafer on Film



Wafer in Box



Tape and Reel



Die in Waffle Pack

